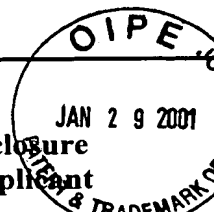


Form 1449 (Modified)

**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)



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Applicant:

Satya, et al

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Group

2858

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Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
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	C3	
Examiner <i>Quynh</i>		Date Considered 10/31/02

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.